

+ Features

- High density 1 RU platform.
- Hardened -20 to + 75 C version available
- Supports 4 rear facing modules and one power supply
- Identical slots can support any configuration
- AC or DC power supply
- SNMP remote monitoring

⚙ Applications

The TranScend platform has been deployed for numerous applications:

- Node Segmentation
- Distribution Networks
- RFoG Applications
- FTTx Networks
- Long Haul Super-Trunking

Front View



Rear View



with Four
Module Types

Key Benefits

- High packaging density platform.
- Hardened chassis available for -20 to +75 C operating temperatures.
- Identical slots enables any combination of modules to be installed in any slot.
- Available modules:
 - EDFAs
 - Optical and RF Switches
 - Quad Frequency Stackers
 - Quad Frequency Destackers
 - Quad Return Receivers
 - Forward Receivers
 - 1550nm Direct modulated Transmitters

The TranScend Chassis platform features high packaging density, flexibility and operational simplicity. The 1-RU chassis accommodates AC or DC power supplies and up to four modules. It is available in standard (TSD) or hardened (TSH) versions for extreme temperature operation over -20 to +75C.

The TranScend chassis can be stacked directly on top of each other with no air gap making it an ideal platform for applications where rack space is at a premium.

All slots are identical so any combination of modules can be installed in any slot, allowing for ease of installation and future growth. Integrated software allows for remote monitoring of all the modules via SNMP.